



Features

- High isolation 3750 VRMS
- Patented coplanar structure DMC-Isolator®
- Various CTR selection available
- DC input with transistor output
- Operating temperature range 55 °C to 110 °C
- External Creepage ≥ 5.0mm
- Distance Through Isolation ≥ 0.4mm
- Clearance Distance ≥ 5.0mm
- RoHS and REACH Compliance
- Halogen Free Compliance
- MSL class 1
- Regulatory Approvals
 - ✓ UL UL1577 (E364000)
 - ✓ VDE EN60747-5-5 (VDE0884-5)
 - ✓ CQC GB4943.1, GB8898 (19001231775)
 - ✓ IEC62368 (FI/41119)

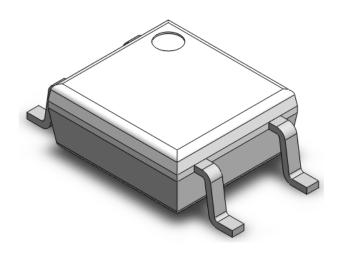
Description

The CT357 series of general purpose optocoupler consists of a photo transistor optically coupled to an Infrared-emitting diode in a 4-lead Mini-Flat DMC-Isolator® package with bending option.

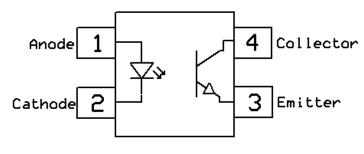
Applications

- DC-DC Converters
- Programmable controllers
- Telecommunication equipment
- Hybrid substrates that require high density mounting

Package Outline



Schematic







Absolute Maximum Ratings $T_A = 25^{\circ}C$, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	3750	V _{RMS}	
T _{OPR}	Operating temperature	-55 ~ +110	°C	
T _{STG}	Storage temperature	-55 ~ +150	°C	
T _{SOL}	Soldering temperature (For 10 seconds)	260	°C	
Ртот	Total power dissipation	200	mW	
Emitter		•	•	
I _F	Forward current	50	mA	
I _{F(TRANS)}	Peak transient current (≤1µs P.W,300pps)	1	А	
V _R	Reverse voltage	6	V	
P _D	Power dissipation	70	mW	
Detector		•	•	
Pc	Power dissipation	150	mW	
B _{VCEO}	Collector-Emitter Breakdown Voltage	80	V	
B _{VECO}	Emitter-Collector Breakdown Voltage	7	V	
Ic	Collector Current	50	mA	



Electrical Characteristics $T_A = 25$ °C, unless otherwise specified

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA	-	1.24	1.4	V	
I _R	Reverse Current	V _R = 6V	-	-	5	μΑ	
Cin	Input Capacitance	f= 1MHz	-	10	250	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
B _{VCEO}	Collector-Emitter Breakdown	I _C = 100μA	80	-	-	V	
Bveco	Emitter-Collector Breakdown	I _E = 100μA	7	-	-	V	
ICEO	Collector-Emitter Dark Current	V _{CE} = 20V, I _F =0mA	-	-	100	nA	

Transfer Characteristics

Symbol	Parameters	3	Test Conditions	Min	Тур	Max	Units	Notes
	Current Transfer Ratio CT357	CT357	IF= 5mA, VCE= 5V	50	-	600	%	
		CT357A		80	-	160		
CTR		CT357B		130	-	260		
		CT357C		200	-	400		
		CT357D		300	-	600		
\/	Collector-Emitter Saturation		I _F = 20mA, I _C = 1mA		0.06	0.2	V	
VCE(SAT)	Voltage		IF= ZUITIA, IC= IIIIA	-	0.00	0.2	V	
R _{IO}	Isolation Resistance		V _{IO} = 500V _{DC} , 40 ~ 60% R.H.	5x10 ¹⁰	-	-	Ω	
Сю	Isolation Capacitance		f= 1MHz	-	0.5	1	pF	

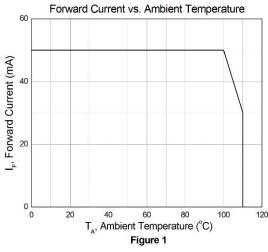
Switching Characteristics

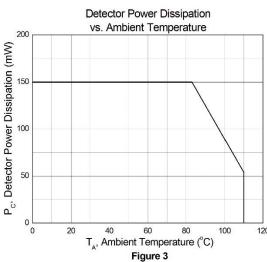
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
tr	Rise Time	L 2m/ V 2V/ B 1000	-	6	18	0	
t _f	Fall Time	I_{C} = 2mA, V_{CE} = 2V, R_{L} = 100 Ω		8	18	μS	

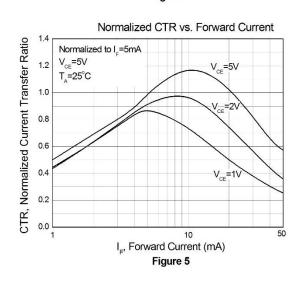


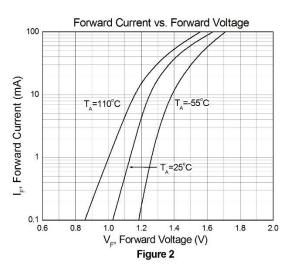


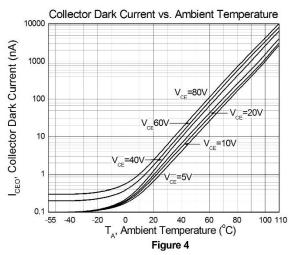
Typical Characteristic Curves T_A = 25°C, unless otherwise specified

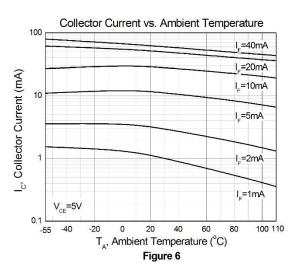








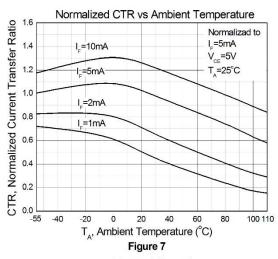


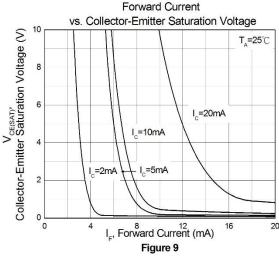


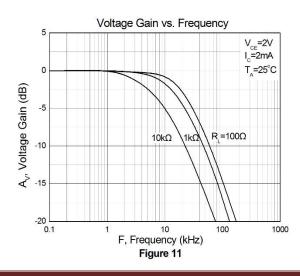


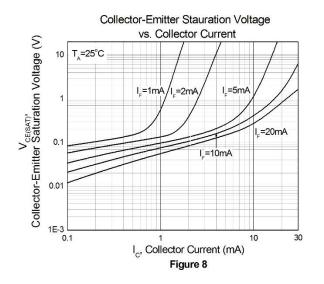


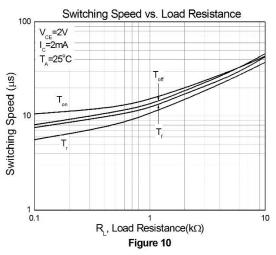
Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified (Continued)













Test Circuit

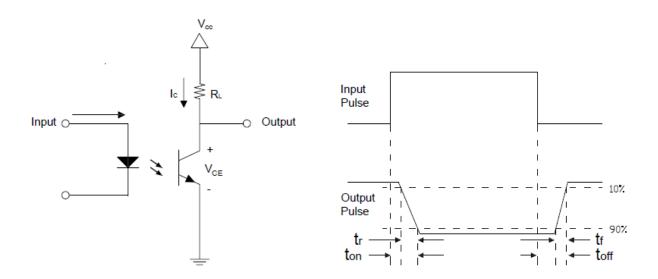
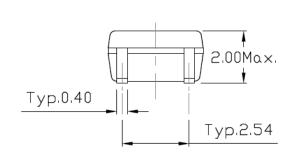


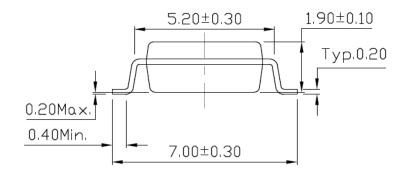
Figure 12: Switching Time Test Circuit

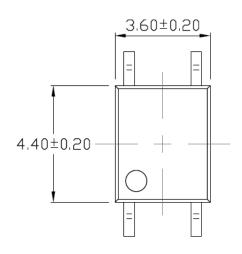


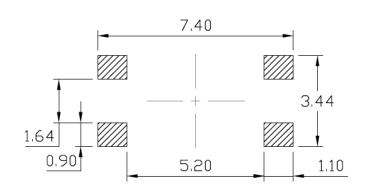


Package Dimension Dimensions in mm unless otherwise stated

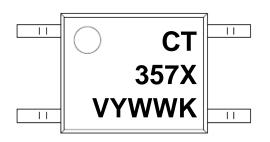








Marking Information



Note:

CT : Denotes "CT Micro"

357 : Part Number

X : CTR Rank (Blank, A, B, C or D)
V : VDE Safety Mark (Blank or V)

Y : One Digit Year Code
WW : Two Digit Work Week
K : Manufacturing Code





Ordering Information

CT357X(V)(Z)

CT = Denotes "CT Micro"

357 = Part Number

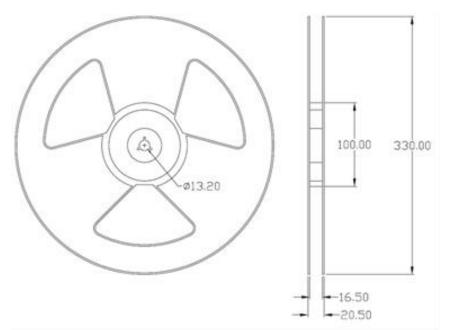
X = CTR Rank Option (Blank, A, B, C or D)V = VDE Safety Mark Option (Blank or V)

Z = Tape and Reel Option (T1 or T2)

Option	Description	Quantity
T1	Surface Mount Lead Forming – With Option 1 Tapping	3000 Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Tapping	3000 Units/Reel

Reel Dimension Dimensions in mm unless otherwise stated

Option T1 / T2

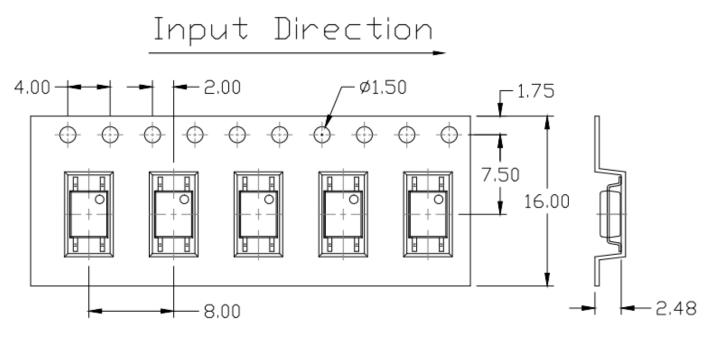




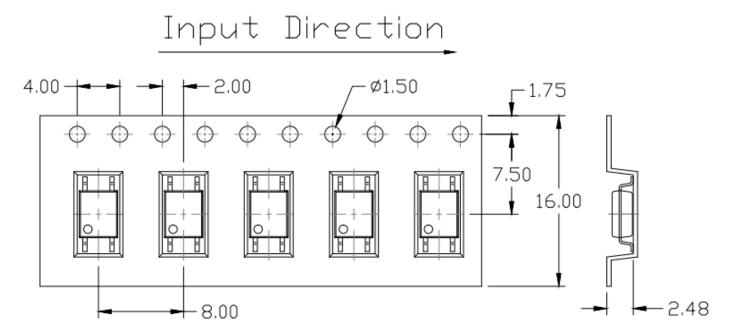


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option T1



Option T2





Solderability Specification (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (Follow the JEDEC standard JESD22-A111)

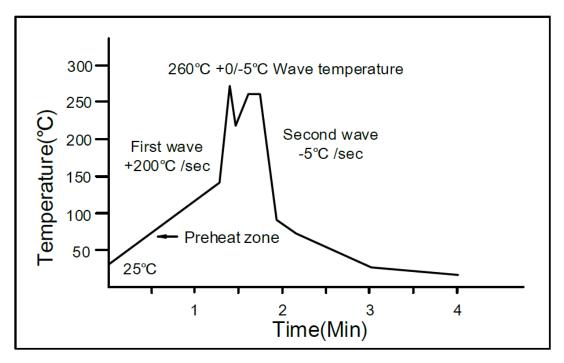
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



Iron Soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

One time soldering is recommended.

Temperature: 350±10°C

Time: 5 sec max.

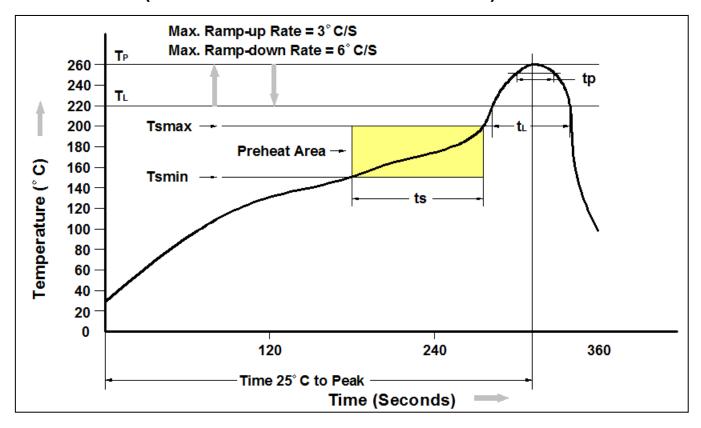
Rev.8

Apr, 2023



DC Input 4-Pin Mini-Flat DMC-Isolator® Phototransistor Optocoupler

Reflow Profile (Follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



CT357 Series

DC Input 4-Pin Mini-Flat DMC-Isolator® Phototransistor Optocoupler

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